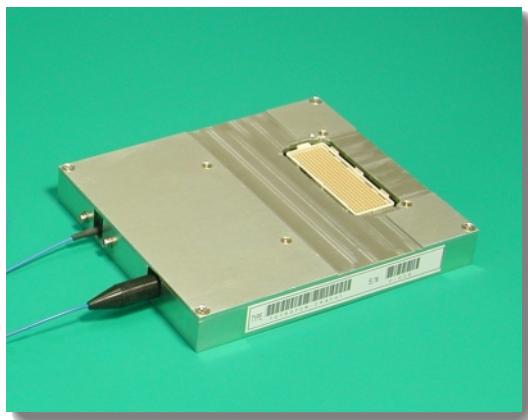
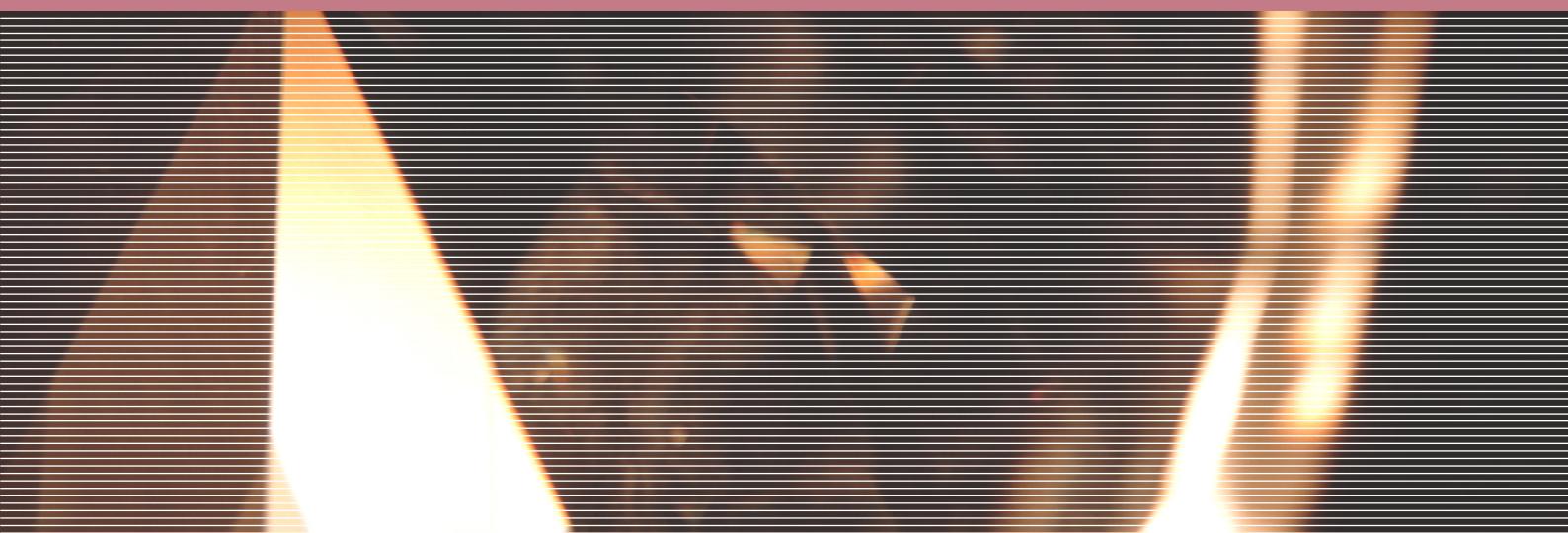


Optical Communication Devices

10 Gb/s Optical Transponder

TOTR370M-IR Series



APPLICATIONS

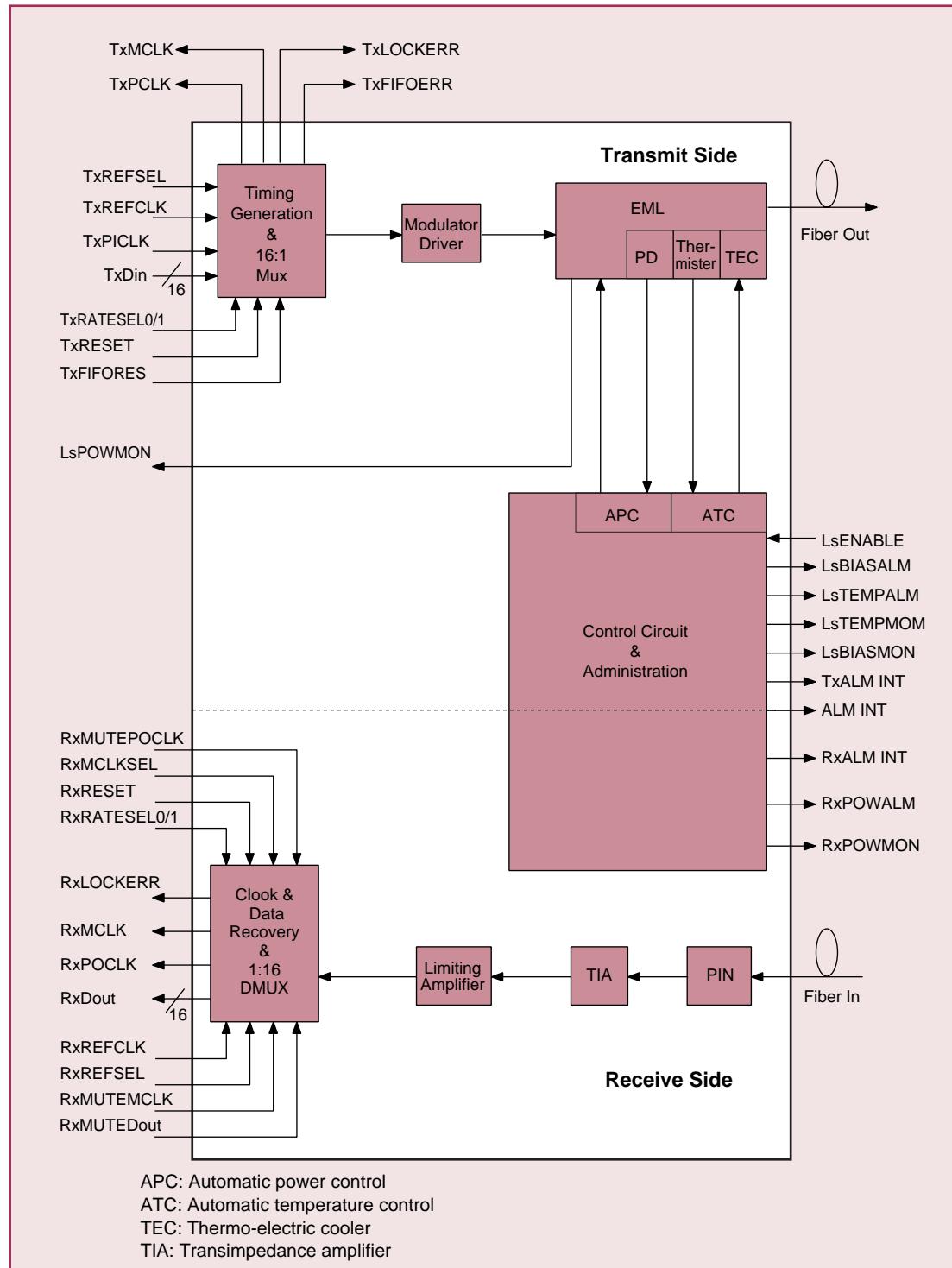
- SONET / SDH (OC-192 / STM-64) applications
- TOTR370M-IRA: Intra-office/Short-Reach
- TOTR370M-IRB: Short-haul/ Intermediate-Reach

FEATURES

- 10 Gb/s optical transceiver with 16 Channel Mux and DeMux
- Optical data rates: 9.953 Gb/s, 10.3 Gb/s, 10.664 Gb/s, 10.709 Gb/s (Selectable)
- Differential LVDS 622 Mb/s data and 622 MHz clock interface
- Optical input power range ● Optical output power range
 TOTR370M-IRA: -17 to 0 dBm (@ BER = 10^{-12} , 9.953Gb/s) TOTR370M-IRA: -4.0 to -2.0 dBm
 TOTR370M-IRB: -17 to 0 dBm (@ BER = 10^{-12} , 9.953Gb/s) TOTR370M-IRB: -0.5 to +1.5 dBm
- T_c : 0 °C to 70 °C
- Power supply: +5.0 V, +3.3 V and -5.2 V
- Package size: 4 x 3.5 x 0.53 inch (101.6 x 88.9 x 13.4 mm)
- Wavelength: 1530 to 1565 nm (C-band)
- Lower power consumption: 6W (typ.)
- Meg-Array® 300-pin receptacle
- Target distance
 TOTR370M-IRA: 25 km (500ps/nm)
 TOTR370M-IRB: 40 km (800ps/nm)

TOTR370M-IR Series

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Ratings	Unit
Storage temperature	T_{stg}	-40 to +85	°C
Input data signal voltage	V_i	-0.5 to $V_{DD}+0.5$	V
Input optical peak power	-	6	dBm
Input optical average power	-	3	dBm
Positive supply 1 voltage	V_{CC}	0 to 6	V
Positive supply 2 voltage	V_{DD}	-0.5 to +3.8	V
Negative supply voltage	V_{EE}	-6.5 to +0.3	V

ELECTRICAL AND OPTICAL CHARACTERISTICS (BOL)

Operating Temperature

Item	Min	Typ.	Max	Unit
Operating case temperature range	0	–	+70	°C

Optical Characteristics

Item	Min	Typ.	Max	Unit
Target distance	TOTR370M-IRA	–	25	–
	TOTR370M-IRB	–	40	–
Dispersion	TOTR370M-IRA	–	–	500
	TOTR370M-IRB	–	–	800
Operating wavelength range	1530	–	1565	nm
Transmitter				
Spectral Width (@ 20 dB down)	–	–	1.0	nm
Side mode suppression ratio	30	–	–	dB
Optical fiber output power	TOTR370M-IRA	–4.0	–	–2.0
	TOTR370M-IRB	–0.5	–	+1.5
Extinction ratio	9	–	–	dB
Optical return loss	30	–	–	dB
Receiver				
Sensitivity (@ BER = 10 ⁻¹² , 25°C, 9.95328 Gb/s)	–	–	–17	dBm
Overload	0	–	–	dBm
Reflectance	27	–	–	dB
Optical path penalty (@ Target distance)	–	–	2	dB

Electrical Power Supplies

Item	Symbol	Min	Typ.	Max	Unit
Positive supply 1 voltage	V _{CC}	+4.75	+5.0	+5.25	V
Positive supply 1 current	I _{CC}	–	–	120	mA
Positive supply 2 voltage	V _{DD}	+3.135	+3.3	+3.465	V
Positive supply 2 current	I _{DD}	–	–	2700	mA
Negative supply voltage	V _{EE}	–5.46	–5.2	–4.94	V
Negative supply current	I _{EE}	–	–	850	mA

Input Data/Clock signals (LVDS)

Item	Symbol	Conditions	Min	Typ.	Max	Unit
Input common mode voltage	V _{Cm}	Avg	0	1200	2400	mV
Input peak differential voltage	V _{Dif}	V _p -V _{in}	100	–	800	mV
Differential input impedance	R _{in}	f = 622.08 MHz	80	100	120	Ω

Output Data/Clock signals (LVDS)

Item	Symbol	Conditions	Min	Typ.	Max	Unit
Output voltage high	V _{oh}	R _{load} = 100 Ω	–	–	1475	mV
Output voltage low	V _{ol}	R _{load} = 100 Ω	925	–	–	mV
Output differential voltage	V _{od}	R _{load} = 100 Ω	250	–	400	mV
Output offset voltage	V _{os}	R _{load} = 100 Ω	1125	–	1275	mV
Differential output impedance	R _o	V _{Cm} = 1.0V and V _{cm} = 1.4V	80	100	280	Ω

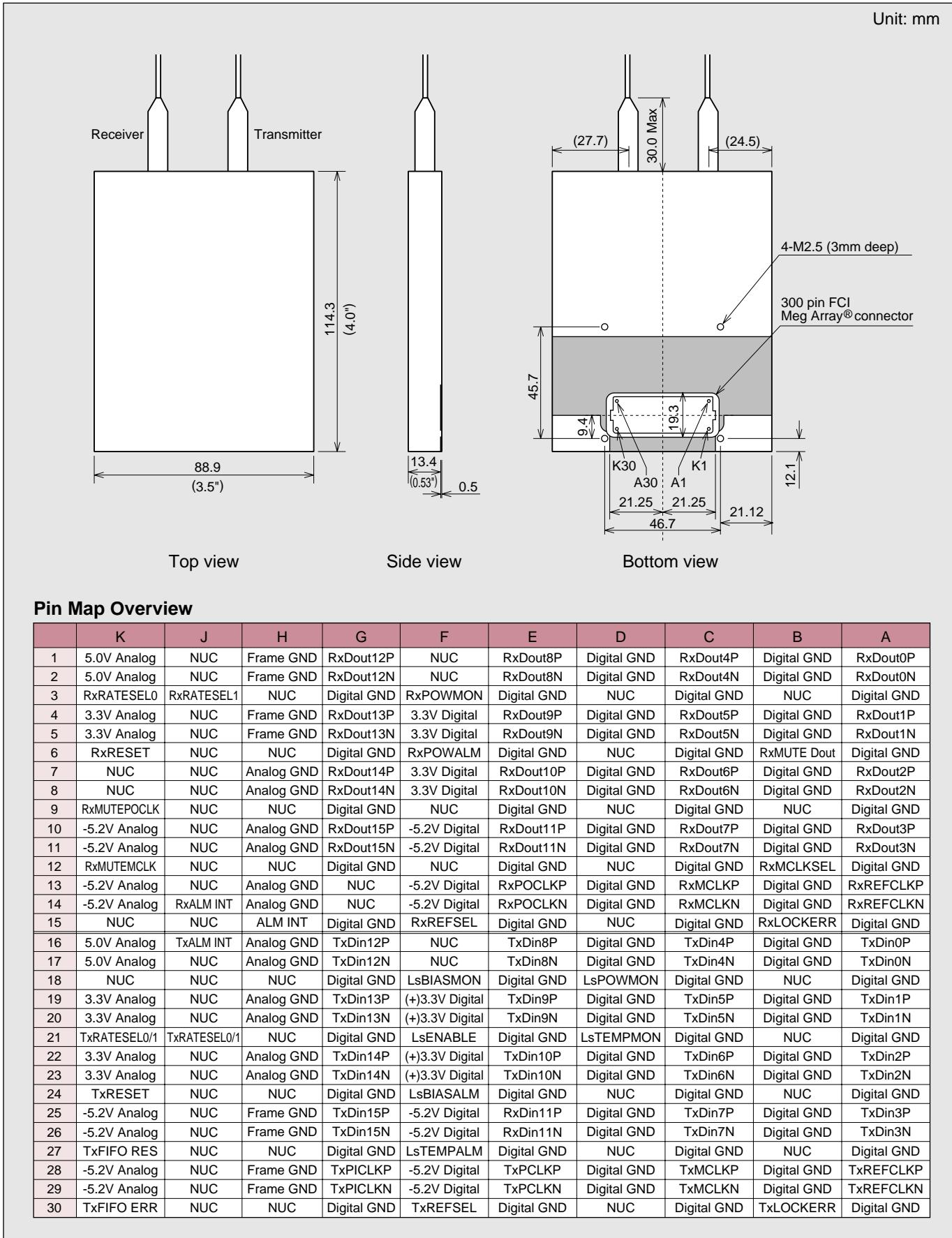
Electrical Input and Output Signals (Digital Signal Characteristics)

Item	Min	Typ.	Max	Unit
Alarm output high level	V _{DD} -0.5	–	V _{DD}	V
Alarm output low level	GND	–	0.5	V
Control input high level	V _{DD} -1.0	–	V _{DD}	V
Control input low level	GND	–	0.8	V

Electrical Input and Output Signals (Analog Signal Characteristics)

Item	Symbol	Min	Typ.	Max	Unit
Input power monitor voltage slope for PIN	R _x PWMON	0.8	–	1.26	V/mW
Normalized laser power monitor voltage	L _s PWMON	0.44	–	0.56	V
Laser disable mode	–	–20	–	20	mV
Laser monitor bias voltage slope	L _s BiasMON	17.8	–	22.5	mV/mA
Laser monitor bias offset voltage	–	–20	–	20	mV

DIMENSIONAL OUTLINE AND PIN ASSIGNMENT



Control Tables

TxRATESEL1 (J 21)	TxRATESEL0 (K 21)	
0	0	10 Gb Ethernet rate of 10.3 Gb/s selected
0	1	TBD
1	0	FEC rate of 10.664 Gb/s and 10.709Gb/s selected
1	1	normal SONET rate of 9.953 Gb/s selected
TxREFSEL (F 30)		
0		slects a TxREFCLK frequency of 155MHz
1		slects a TxREFCLK frequency of 622MHz
LsENABLE (F 21)		
0		normal operation
1		laser disable
TxRESET (K 24)		
0		asynchronous Mux system reset
1		normal operation
TxFIFOES (K 27)		
0		Mux FIFO reset
1		normal operation
RxRATESEL1 (J 3)	RxRATESEL0 (K 3)	
0	0	10 GB Ethernet rate of 10.3 Gb/s selected
0	1	TBD
1	0	FEC rate of 10.664 Gb/s and 10.709Gb/s selected
1	1	normal SONET rate of 9.953 Gb/s selected
RxREFSEL (F 15)		
0		slects an RxREFCLK frequency of 155MHz
1		slects an RxREFCLK frequency of 622MHz
RxMCLKSEL (B 12)		
0		slects the RxMCLK frequency of 155MHz
1		slects the RxMCLK frequency of 622MHz
RxMUTEPOCLK (K 9)		
0		mutes the RxPOCLK
1		normal operation
RxMUTEMCLK (K 12)		
0		mutes the RxMCLK
1		normal operation
RxMUTEDout (B 6)		
0		mutes the RxDout[0:15]
1		normal operation
RxRESET (K 6)		
0		asynchronous DeMux system reset
1		normal operation

Note: When the input pins are open, these input logic signals are internally applied to each input pin by pull-up and pull-down circuitry in the module.

Alarm Tables

ALM INT (H 15)		
0		indicates alarm active
1		normal operation
TxALM INT (J 16)		
0		indicates alarm active
1		normal operation
RxALM INT (J 14)		
0		indicates alarm active
1		normal operation
TxFIFOERR (K 30)		
0		indicates a Mux FIFO error
1		normal operation
TxLOCKERR (B 30)		
0		indicates loss of PLL lock
1		normal operation
LsBIASALM (F 24)		
0		laser bias alarm active
1		normal operation
LsTEMPALM (F 27)		
0		laser temperature alarm active
1		normal operation
RxPOWALM (F 6)		
0		indicates alarm active
1		normal operation
RxLOCKERR (B 15)		
0		indicates loss of PLL lock
1		normal operation

PRECAUTIONS

- (a) Power supply: Transient electric spike may cause a damage to the laser, the photodiode or IC chips. A surge-free power supply and a slow starter circuit should be used.
To avoid causing an electrical surge, pins should not be connected or disconnected on the test fixture before turning power off.
- (b) The product should be grounded for obtaining the performance.
- (c) Safety: The laser emits invisible light harmful to the human eyes. Direct viewing should be avoided.

OVERSEAS SUBSIDIARIES AND AFFILIATES

011025 (X)

Toshiba America Electronic Components, Inc.

Headquarters-Irvine, CA
9775 Toledo Way, Irvine, CA 92618, U.S.A.
Tel: (949)455-2000 Fax: (949)859-3963

Deerfield, IL(Chicago)
One Pkwy., North, Suite 500, Deerfield,
IL 60015, U.S.A.
Tel: (847)945-1500 Fax: (847)945-1044

Edison, NJ
2035 Lincoln Hwy. #3000, Edison.
NJ 08817, U.S.A.
Tel: (732)248-8070 Fax: (732)248-8030

Raleigh, NC
5511 Capitol Center Dr., #114,
Raleigh, NC 27606, U.S.A.
Tel: (919)859-2800 Fax: (919)859-2898

Richardson, TX(Dallas)
777 East Campbell Rd., #650, Richardson,
TX 75081, U.S.A.
Tel: (972)480-0470 Fax: (972)235-4114

Wakefield, MA(Boston)
401 Edgewater Place, #360, Wakefield,
MA 01880, U.S.A.
Tel: (781)224-0074 Fax: (781)224-1095

Toshiba Electronics Europe GmbH

Düsseldorf Head Office
Hansaallee 181, D-40549 Düsseldorf,
Germany
Tel: (0211)5296-0 Fax: (0211)5296-400

Toshiba Electronics Italiana S.R.L.
Centro Direzionale Colleoni,
Palazzo Perseo 3,
1-20041 Agrate Brianza, (Milan), Italy
Tel: (039)68701 Fax:(039)6870205

Toshiba Electronics(UK) Ltd.
Riverside Way, Camberley Surrey,
GU15 3YA, U.K.
Tel: (01276)69-4600 Fax: (01276)69-4800

Toshiba Electronics Scandinavia A.B.
Gustavslundsvägen 12, 2nd Floor,
S-161 15 Bromma, Sweden
Tel: (08)704-0900 Fax: (08)80-8459

**Toshiba Electronics Asia
(Singapore) Pte. Ltd.**

Singapore Head Office
438B Alexandra Road, #06-08/12 Alexandra
Technopark, Singapore 119968
Tel: (278)5252 Fax: (271)5155

Toshiba Electronics Asia, Ltd.

Hong Kong Head Office
Level 11, Tower 2, Grand Century
Place, No.193, Prince Edward Road West,
Mong Kok, Kowloon, Hong Kong
Tel: 2375-6111 Fax: 2375-0969

Beijing Office
Rm 714, Beijing Fortune Building,
No.5 Dong San Huan Bei-Lu, Chao Yang District,
Beijing, 100004, China
Tel: (010)6590-8796 Fax: (010)6590-8791

**Toshiba Electronics Korea
Corporation**

Seoul Head Office
14/F, KEC B/D, 275-7 Yangjae-dong,
Seocho-ku, Seoul, Korea
Tel: (02)589-4300 Fax: (02)589-4302

**Toshiba Technology Development
(Shanghai) Co., Ltd.**
23F, HSBC Tower, 101
Yin Cheng East Road, Pudong New Area, Shanghai,
200120, China
Tel: (021)6841-0666 Fax: (021)6841-5002

**Toshiba Electronics Taiwan
Corporation**

Taipei Head Office
17F, Union Enterprise Plaza Bldg. 109
Min Sheng East Rd., Section 3, 10446 Taipei,Taiwan
Tel: (02)2514-9988 Fax: (02)2514-7892

(As of August, 2001)

The information contained herein is subject to change without notice.

The information contained herein is presented only as a guide for the applications of our products.
No responsibility is assumed by TOSHIBA for any infringements of patents or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of TOSHIBA or others.

TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc..

The Toshiba products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.).
These Toshiba products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of Toshiba products listed in this document shall be made at the customer's own risk.

The products described in this document are subject to the foreign exchange and foreign trade laws.
Gallium arsenide (GaAs) is a substance used in some of the products described in this documents. GaAs dust and fumes are toxic. Do not break, cut or pulverize the products, or use chemicals to dissolve them.
When disposing of the products, follow the appropriate regulations. Do not dispose of the products with other industrial waste or with domestic garbage.

Website: <http://www.semicon.toshiba.co.jp/eng/index.html>

In Touch with Tomorrow
TOSHIBA

TOSHIBA CORPORATION

Electronic Devices Sales & Marketing Division
1-1, Shibaura 1-chome, Minato-ku, Tokyo, 105-8001, Japan
Tel: +81-3-3457-3405 Fax: +81-3-5444-9431

©2002 TOSHIBA CORPORATION
Printed in Japan